ABSTRACT OF THE DISCLOSURE

FACE-TO-FACE MULTI-CHIP PACKAGE

A face-to-face multi-chip chip scale package. A flip chip technique is employed. More than one chip can be disposed into one package. Bumps are formed to achieve electrical connection between the chips. An anisotropic conductive paste can be filled between the chips to improve the electrical connection between the chips. A flip chip technique is employed, so that the pads distributed on the chips can be designed as an area array, so as to increase the package integration. To further improve the performance, a heat dissipation apparatus is installed on the rear side of the chips.

Figure 3A